

### **Reliability and Test Condition**

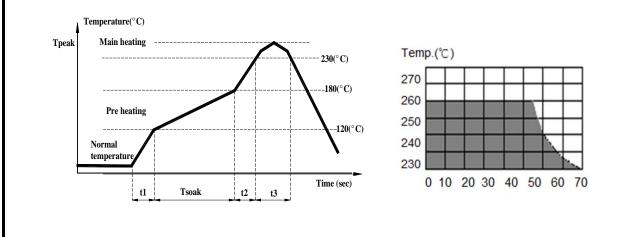
ITEM	SPECIFICATION	TEST CONDITIONS
Operating Temperature	- 55 °C ∼ + 125 °C	
Storage Temperature	- 40 °C ∼ + 85 °C	

#### **Reflow soldering conditions**

Temperature rise gradient	t1	1~5°C/sec
Heating time Heating temperature	Tsoak	$50s \sim 150s$ $120^{\circ}C \sim 180^{\circ}C$
Time over 230°C	t3	90~120 sec
Slope of temp. rise	t2	1~5°C/sec
Peak temperature Peak hold time	Tpeak	255∼260°C 10sec (max)
	-	No. of mounting 3 times

- Pre-heating should be in such a way that the temperature difference between solder and ferrite surface is limited to 150°C max. Also cooling into solvent after soldering should be in such a way that the temperature difference is limited to 100°C max. Unenough pre-heating may cause cracks on the ferrite, resulting in the deterioration of product quality.
- Products should be soldered within the following allowable range indicated by the slanted line. The excessive soldering conditions may cause the corrosion of the electrode, When soldering is repeated, allowable time is the accumulated time.

#### **Reflow soldering temperature profile**





### **Reliability and Test Condition**

ITEM	SPECIFICATION	TEST CONDITIONS	
Reworking with soldering iron			
• Preheating : $150^{\circ}$ C, 1 minute			
<ul> <li>Tip temperat</li> </ul>	• Tip temperature : $280^{\circ}$ C max.		
• Soldering time : 3 seconds max.			
• Soldering iron output : 30w max.			
• End of soldering iron : $\phi$ 3mm max.			
• Reworking should be limited to only one time.			
Note: Do not directly touch the products with the tip of the soldering iron in order to			
prevent the crack on the ferrite material due to the thermal shock.			
Solder Volume	Solder Volume		
• Solder shall	be used not to be exceed the upper limits as show	vn below.	
Upper Limit			
		- Recommendable	
<ul> <li>Accordingly increasing the solder volume, the mechanical stress to product is also increased. Exceeding solder volume may cause the failure of mechanical or electrical performance.</li> </ul>			

### MECHANICAL CHARACTERISTICS

ITEM	SPECIFICATION	TEST CONDITIONS
Terminal Strength	Terminal strength does not distort the case shall meet SPEC DC resistance specifications.	Solder chip on PCB and applied 10N     (1.02Kgf) for 10 sec.     CHIP BEAD     F
Substrate bending test	SPEC substrate bending test DC resistance shall meet specifications.	<ul> <li>After soldering a chip to a test substrate, bend the substrate by 3mm hold for 10s and then return.</li> <li>Soldering shall be done in accordance with the recommended PC board pattern and reflow soldering.</li> </ul>



## **Reliability and Test Condition**

ITEM	SPECIFICATION	TEST CONDITIONS
Resistance to solder heat	• No visible damage	• Solder Temp. : $265\pm3^{\circ}C$
	• Electrical characteristics and mechanical	• Immersion time : 6±1 sec
	characteristics shall be satisfied.	• Preheating : $100^{\circ}$ C to $150^{\circ}$ C, 1 minute.
		• Measurement to be made after keeping
	Consult standard MIL-STD-202	keeping at room temp for 24±2 hrs.
	METHOD 210	· Solder : Sn-3Ag-0.5Cu
Solderability	• 95% min. coverage of all metabolised area	• Solder Temp. : $240\pm5^{\circ}C$
		• Immersion time : 3±1 sec
	Consult standard J-STD-002	· Solder : Sn-3Ag-0.5Cu

### **Environmental Characteristics**

ITEM	SPECIFICATION	TEST CONDITIONS
High Temperature Resistance	<ul> <li>Appearance : no mechanical damage</li> <li>Inductance shall be with ±20% of the initial value</li> </ul>	<ul> <li>Operate Temperature : 125°C ± 2°C</li> <li>Time : 1000 ±12Hrs</li> <li>Measurement : After placing at room ambient temperature for 24 hours minimum</li> </ul>
Biased Humidity Resistance	<ul> <li>Appearance : no mechanical damage</li> <li>Inductance shall be with ±20% of the initial value</li> </ul>	<ul> <li>Humidity : 85 ± 5% RH</li> <li>Temperature : 85°C ± 2°C</li> <li>Time : 1000 ±12Hrs</li> <li>Measurement : After placing at room ambient temperature for 24 hours minimum</li> </ul>
Temperature Cycle	<ul> <li>Appearance : no mechanical damage</li> <li>Inductance shall be with ±20% of the initial value</li> </ul>	<ul> <li>Low Temperature : -55 ± 5°C kept stabilized for 30 minutes each</li> <li>High Temperature : 125 ± 5°C kept stabilized for 30 minutes each</li> <li>Cycle : 1000 cycles</li> <li>Measurement : After placing for 24 hours minimum at room ambient temperature</li> <li>step155°C temp±5°C 30±3 minutes</li> <li>step2. Room temperature 2 to 5 minutes</li> <li>step3. +125°C temp±5°C 30±3 minutes</li> <li>step4. Room temperature 2 to 5 minutes</li> </ul>
Vibration test	<ul> <li>Appearance : no mechanical damage</li> <li>Inductance shall be with ±20% of the initial value</li> </ul>	<ul> <li>Frequency and Amplitude : 10-2000-10Hz</li> <li>Direction : X, Y, Z.</li> <li>Test duration : 4 hours for each direction, 12 hours in total.</li> </ul>



# **Reliability and Test Condition**

ITEM	SPECIFICATION	TEST CONDITIONS
Mechanical Shock Test Operational Life	<ul> <li>Appearance : no mechanical damage</li> <li>Inductance shall be with ±20% of the initial value</li> </ul>	<ul> <li>peak acceleration : 100g's</li> <li>Duration of pulse : 6 ms</li> <li>Waveform : Half-sine</li> <li>Velocity change : 12.3 ft/sec</li> <li>Direction : X , Y , Z (3 axes/3 times)</li> <li>Temperature : 125°C ± 2°C</li> </ul>
	<ul> <li>Appearance : no mechanical damage</li> <li>Inductance shall be with ±20% of the initial value</li> </ul>	<ul> <li>Temperature : 125 C ± 2 C</li> <li>Time : 1000 ±12Hrs</li> <li>Measurement : After placing at room ambient temperature for 24 hours minimum</li> </ul>
Electrostatic discharge test	<ul> <li>Appearance : no mechanical damage</li> <li>Inductance shall be with ±20% of the initial value</li> </ul>	<ul> <li>ESD voltage ; 15K Volts</li> <li>Mode 1 : 150 pF / 330 Ohm</li> <li>Mode 2 : 150 pF / 2000 Ohm</li> </ul>